

KAA-3528SURKMGKC HYPER RED

MEGA GREEN

Features

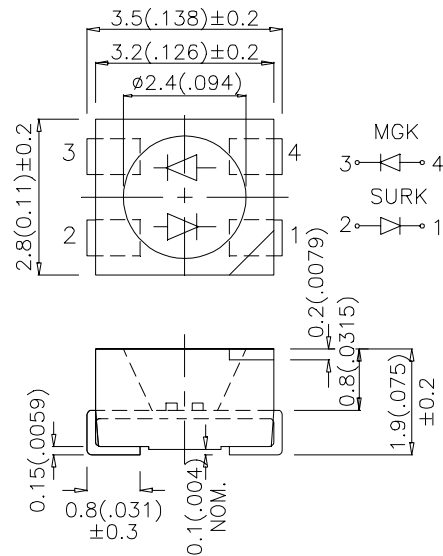
- BOTH CHIPS CAN BE CONTROLLED SEPARATELY.
- SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- AVAILABLE ON TAPE AND REEL.
- IDEAL FOR BACKLIGHTING.
- PACKAGE: 1500PCS / REEL.

Description

The Hyper Red source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

The Mega Green source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
3. Lead spacing is measured where the lead emerge package.
4. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	2θ1/2
KAA-3528SURKMGKC	HYPHER RED (InGaAlP)	WATER CLEAR	80	210	120°
	MEGA GREEN (InGaAlP)		40	70	

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at T_A=25°C

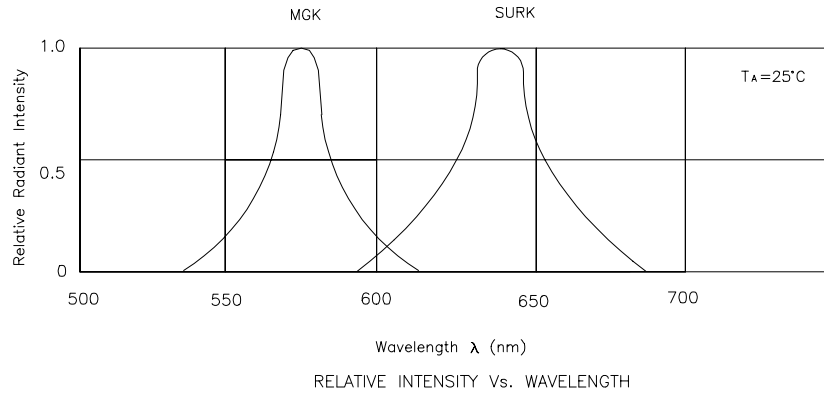
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ _{peak}	Peak Wavelength	Hyper Red Mega Green	640 574		nm	IF=20mA
λ _D	Dominate Wavelength	Hyper Red Mega Green	630 570		nm	IF=20mA
Δλ _{1/2}	Spectral Line Halfwidth	Hyper Red Mega Green	28 20		nm	IF=20mA
C	Capacitance	Hyper Red Mega Green	35 15		pF	VR=0V;f=1MHz
V _F	Forward Voltage	Hyper Red Mega Green	1.95 2.1	2.5 2.5	V	IF=20mA
I _R	Reverse Current	All		10	uA	VR = 5V

Absolute Maximum Ratings at T_A=25°C

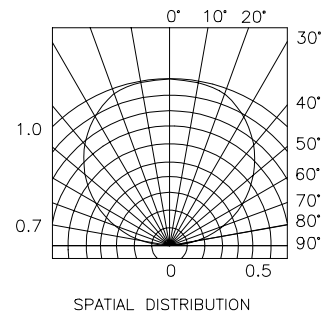
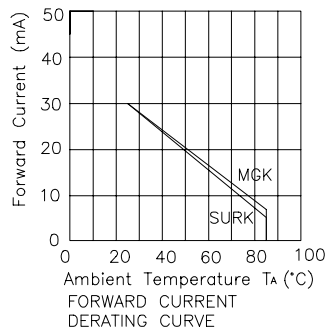
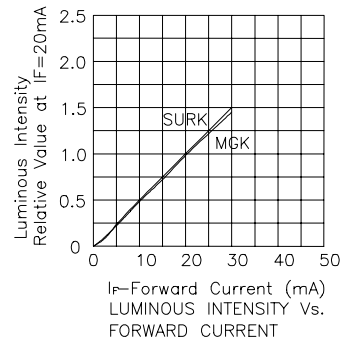
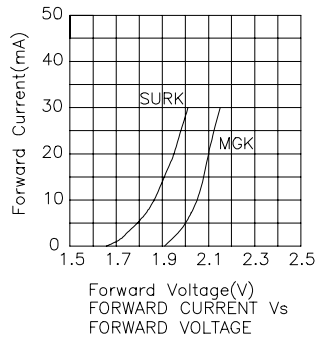
Parameter	Hyper Red	Mega Green	Units
Power dissipation	170	105	mW
DC Forward Current	30	30	mA
Peak Forward Current [1]	185	205	mA
Reverse Voltage	5	5	V
Operating/Storage Temperature	-40°C To +85°C		

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

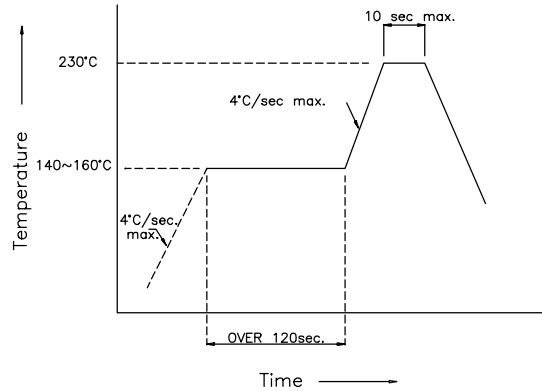


Hyper Red / Mega Green KAA-3528SURKMGKC

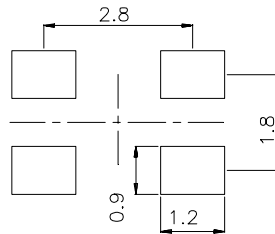


KAA-3528SURKMGKC SMT Reflow Soldering Instruction

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)

